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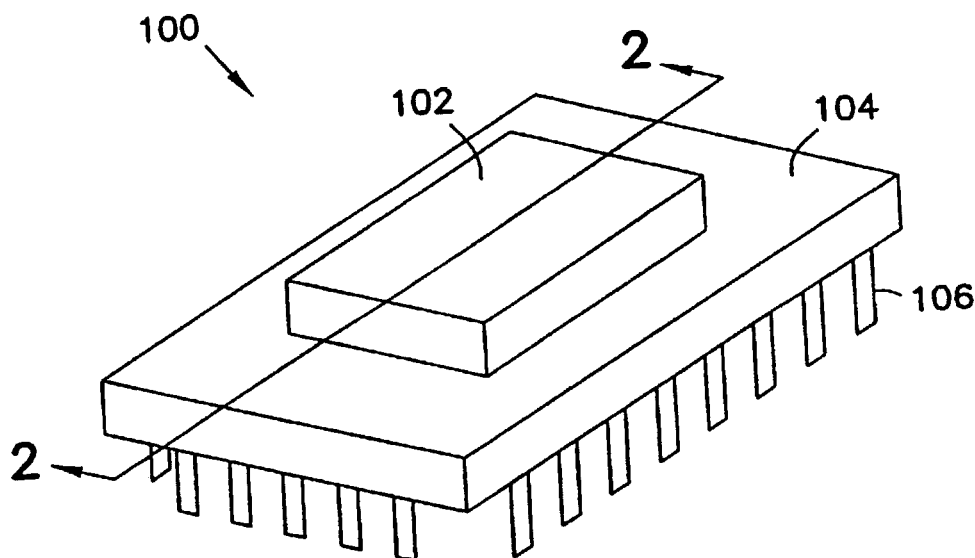
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(54) Title: INTEGRATED CIRCUIT PACKAGE



(57) **Abstract:** An integrated circuit package is provided that includes a multi-layer organic substrate. The substrate has conductive vias provided between isolated conductive layers. The vias are formed using a laser to cut through a dielectric layer separating the conductive layers. External interconnects in the form of T-shaped pins are soldered to the substrate of the integrated circuit package. An integrated circuit can be attached to the substrate using a flip-chip technique.

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